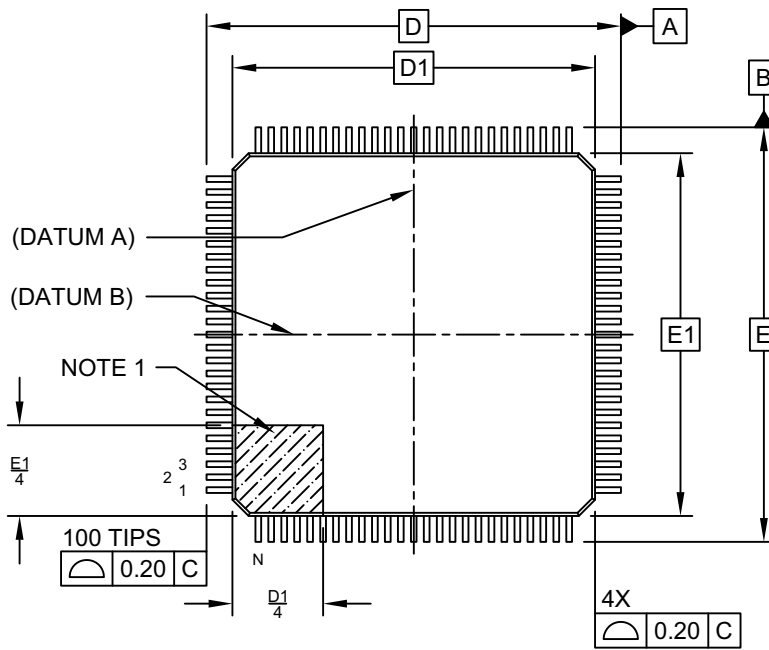
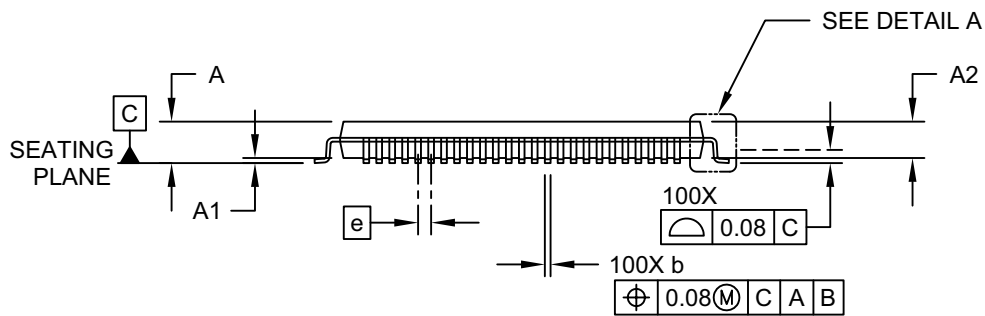


**100-Lead Low Profile Quad Flatpack (PL) - 14x14 mm Body [LQFP]**

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



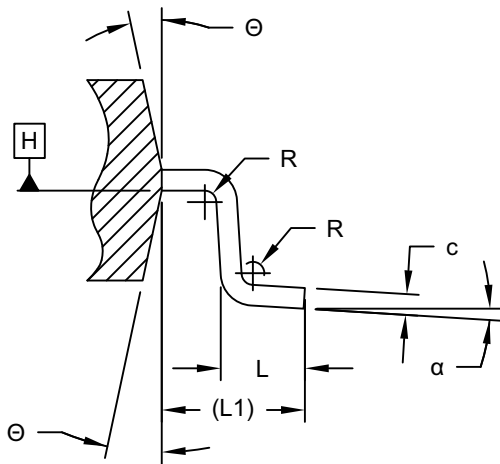
TOP VIEW



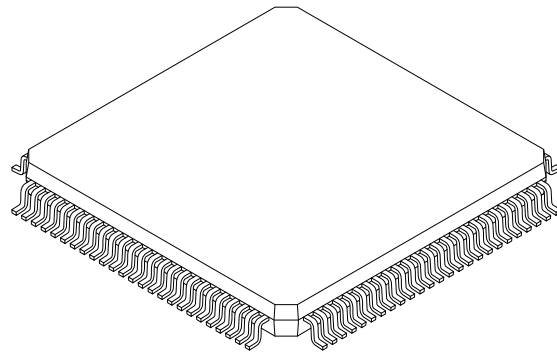
SIDE VIEW

**100-Lead Low Profile Quad Flatpack (PL) - 14x14 mm Body [LQFP]**

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



DETAIL A



Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Number of Leads	N	100		
Pitch	e	0.50 BSC		
Overall Height	A	-	-	1.60
Standoff	A1	0.05	-	0.15
Molded Package Thickness	A2	1.35	-	1.45
Overall Length	D	16.00 BSC		
Molded Package Length	D1	14.00 BSC		
Overall Width	E	16.00 BSC		
Molded Package Width	E1	14.00 BSC		
Lead Width	b	0.17	0.22	0.27
Lead Thickness	c	0.09	-	0.20
Lead Length	L	0.45	0.60	0.75
Footprint	(L1)	1.00 REF		
Mold Draft Angle	$\Theta$	11°	12°	13°
Lead Angle	$\alpha$	0°	3.5°	7°
Bend Radius	R	0.08	-	-

Notes:

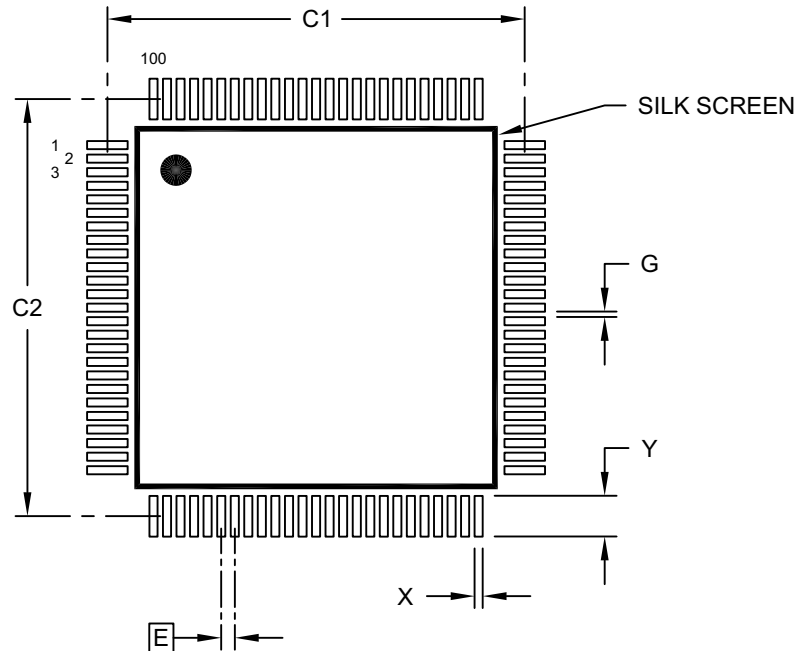
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

**100-Lead Low Profile Quad Flatpack (PL) - 14x14 mm Body [LQFP]**

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



**RECOMMENDED LAND PATTERN**

Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	0.50 BSC		
Contact Pad Spacing	C1		15.40	
Contact Pad Spacing	C2		15.40	
Contact Pad Width (X100)	X			0.30
Contact Pad Length (X100)	Y			1.50
Space Between Pads	G	0.20		

**Notes:**

1. Dimensioning and tolerancing per ASME Y14.5M  
BSC: Basic Dimension. Theoretically exact value shown without tolerances.